

Fe/Si nanoparticle acts as a "seed" and the Si filaments grow from the Fe/Si nanoparticle surface. This approach produced wires with a distribution of diameters ranging from 8–40 nm. In order to produce smaller-diameter wires, the researchers developed a post-synthesis approach. They used oxidation at elevated temperature to diffuse oxygen radially inward and shrink the Si crystalline core. Fractions were then separated according to the wire diameter using centrifugal separation. Using this method, the researchers produced a series of four crystalline Si nanowire samples whose most probable diameters were 4.5 ± 0.2 nm, 6.5 ± 0.3 nm, 9.5 ± 0.3 nm, and 23.1 ± 0.7 nm. The researchers probed the phonon bands in these nanowires using Raman spectroscopy at low enough laser intensity that temperature broadening was not a factor. Comparison of the Raman spectra of these Si nanowires showed that with decreasing diameter, the first-order Raman band at ~ 520 cm $^{-1}$ develops a noticeable asymmetry to lower frequency, and the peak position downshifts.

The researchers analyzed their results based on an asymmetric line-shape model developed by Richter with an adjustable parameter (α) added to the theory that defines the width of the Gaussian phonon-confinement function. The researchers found that this parameter is not sensitive to diameter over the 4–25 nm range if they took into account the measured diameter distribution. This result is contradictory to the large range of reported α values. While attributing the difference to a variety of unknown conditions, the researchers said that the thickness and nature of the oxide coating on the wire might also impact the phonon confinement. That is, they said, the phonon in the crystalline core of the nanowire has to decay into phonons in the oxide shell. Therefore, the researchers suggested future experiments on hydrogen-terminated Si nanowires to see how hydrogen termination affects the value of the confinement parameter.

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Bulk Metallic Glass Foam Achieves High Ductility

Metallic foams are currently used as ultralight structural materials. Bulk metallic glasses (BMGs) show exceptional strength and elasticity, in addition to other favorable properties, rendering them also useful for structural applications and potentially for biocompatible implants. A.H. Brothers and D.C. Dunand of Northwestern University considered, then, whether BMG foams offer unique opportunities in engineering structures or bio-

medical implants. They have found that Vit106 ($Zr_{57}Nb_5Cu_{15.4}Ni_{12.6}Al_{10}$) foam shows compressive properties not unlike ductile aluminum foam, despite a lack of ductility in monolithic Vit106. Furthermore, Vit106 contains neither precious metals nor toxic beryllium, and shows biocompatibility.

As reported in the February 18 issue of *Advanced Materials* (p. 484, DOI: 10.1002/adma.200400897), the researchers produced samples by crushing optical-grade BaF₂ and sieving it to produce and select 215–220 µm particles. These were then packed into graphite crucibles and sintered at 1250°C for 10 h under high vacuum. The 7-mm-diameter patterns were then placed in stainless steel crucibles and vacuum-dried at 300°C for 30 min. Vit106 charges were then combined with the BaF₂

patterns in preheated crucibles and melted. High-pressure argon gas was applied to the Vit106 surface to drive it into the BaF₂ pattern. After cooling, the Vit106/BaF₂ composite was ground to a desired size and the BaF₂ was leached out using nitric acid. Scanning electron microscope images of Vit106 foams of 4.5 mm diameter and 8.7 mm height show 78% open porosity with pore sizes of 212–250 µm. The thickness of all Vit106 struts is well below 1 mm, where high bending ductility is expected. X-ray diffraction shows that no crystalline phases were present in the foam. The researchers concluded that BMG foams can achieve high compressive ductility through strut bending, in sharp contrast to the brittle compressive behavior of BMG in monolithic form.

VIVEK RANJAN

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Corrections

MRS Bulletin misprinted the sponsors of Symposium LL in the report on the 2004 Materials Research Society Fall Meeting (*MRS Bulletin* 30 [3] [March 2005] p. 239). Support to Symposium LL was given by the Army Research Office (United States of America) and the Engineering and Physical Sciences Research Council (United Kingdom). Following is the corrected report.

Materials Issues in Solid Free-Forming

Symposium LL brought together discussions addressing important issues related to free-forming and other parallel processing methods for advanced materials. The symposium opened with a special address titled "Electrospraying Wings of Molecular Elephants" by John Fenn (Virginia Commonwealth Univ.), 2002 Nobel Laureate in Chemistry. The presentation elucidated the electrospray technique and the significant advantage in the use for weighing large biomolecules. Several sessions followed, with invited papers from a host of eminent scientists from around the world. The first session covered the broad field of solid free-forming, with M. Edirisinghe (Queen Mary, Univ. of London), B. Derby (Univ. of Manchester and UMIST), A. Safari (Rutgers), and L. Iuliano (Politecnico di Torino) presenting talks on jet-based and other advanced materials-forming methods at both the nano- and micrometer scales. The following session covered 3D fabrication and applications (J. Beaman, Univ. of Texas; E. Sachs, MIT; Y. Gogotsi et al., Drexel).

The second day started with a session on processing and fabrication of advanced materials (G. Babini and L. Settineri, Politecnico di Torino). The final session addressed electrohydrodynamic atomization and applications (J. De la Mora, Yale; K.L. Choy, Univ. of Nottingham; M. Brenner, Harvard, and I. Loscertales, Univ. of Malaga).

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Nobel Laureate John Fenn (left) with Suwan Jayasinghe, lead symposium organizer.